

**Helen Zhao**

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**Subject:** FW: TP-Link Technologies Co., Ltd., FCC ID: TE7WN66XG, Assessment NO.: AN06T6000, Notice#1

**From:** eric.wong **Sent:** Thursday, August 10, 2006 7:36 PM

**To:** Helen Zhao

**Cc:** eric.wong; aven.zhou

**Subject:** FW: TP-Link Technologies Co., Ltd., FCC ID: TE7WN66XG, Assessment NO.: AN06T6000, Notice#1

Hello Helen,

Please find the replies below in **BLUE**.

**Thank you!!**

**Eric Wong**

-----Original Message-----

Sent: Monday, July 24, 2006 5:42 PM

Subject: TP-Link Technologies Co., Ltd., FCC ID: TE7WN66XG, Assessment NO.: AN06T6000, Notice#1

Question #1: Please provide additional internal photos to clearly show component side, please add one enlarged photo to show chipset name.

**(ERIC: Please find the updated materials attached)**

Question #2: The block diagram shows RF chipset 2413, while operational description shows RF chipset 2414. Please confirm which one is correct, please modify the document(s) accordingly.

**(ERIC: Please find the updated materials attached, the correct RF chipset should be 2414 FYI.)**

Question #3: The power line conducted emission test setup photos show an extension board was used during the test, so the EUT was tested as stand-alone. Please confirm. If this is the case, please update test report section 6.

**(ERIC: Please find the additional photos showing more clearly of the test setup in the updated report.)**

Question #4: Please provide additional radiated emission test setup photos, at least one close view to show placement of the EUT, antenna and support equipment, please show clearly whether extension board was ever used.

**(ERIC: Please find the additional photos showing more clearly of the test setup in the updated report.)**

Question #5: This device is a mini PCI card, needs to be installed inside a notebook PC. It is not a final product. Additional certification or new certification is required when the device is installed in any host, unless it has got a modular approval as specified in FCC Public Notice DA-00-1407. You may need to submit a modular approval cover letter, in the letter, please address 8 criterias.

**(ERIC: Please find the additional materials provided by the manufacturer addressing the modular approvals condition, FYI this EUT is only entitle for the LMA.)**

Best Regards,  
Helen Zhao

The items indicated above must be submitted before processing can continue on the above referenced application. Failure to provide the requested information within 30 days of the original e-mail date may result in application dismissal and forfeiture of the filing fee.

8/10/2006

Also, please note that partial responses increase processing time and should not be submitted. Any questions about the content of this correspondence should be directed to the e-mail address listed below the name of the sender.